



**CHENMKO ENTERPRISE CO.,LTD**

**2SB1197KPT**

**SURFACE MOUNT  
PNP Switching Transistor**

VOLTAGE 32 Volts CURRENT 0.8 Ampere

Lead free devices

**APPLICATION**

- \* Telephone and professional communication equipment.
- \* Other switching applications.

**FEATURE**

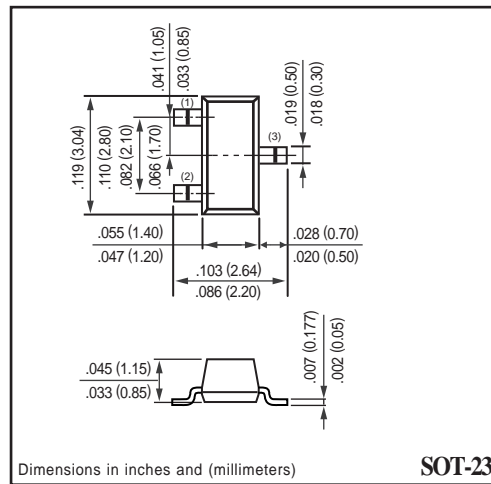
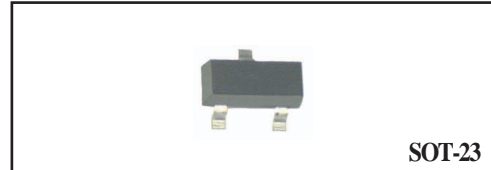
- \* Small surface mounting type. (SOT-23)
- \* Collector peak current (Max.=1000mA).
- \* Suitable for high packing density.
- \* Low voltage (Max.=40V) .
- \* High saturation current capability.
- \* Voltage controlled small signal switch.

**CONSTRUCTION**

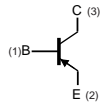
- \* PNP Switching Transistor

**MARKING**

- \* PN @hFE as Q Grade
- \* RC @hFE as R Grade



**CIRCUIT**



**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CB0</sub>	collector-base voltage	open emitter	-	-40	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-32	V
V <sub>EB0</sub>	emitter-base voltage	open collector	-	-5	V
I <sub>C</sub>	collector current DC		-	-0.8	A
I <sub>CM</sub>	peak collector current		-	-1.0	A
I <sub>BM</sub>	peak base current		-	-80	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	-	300	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>j</sub>	junction temperature		-	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

**Note**

1. Transistor mounted on an FR4 printed-circuit board.

## RATING CHARACTERISTIC CURVES ( 2SB1197KPT )

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

### CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

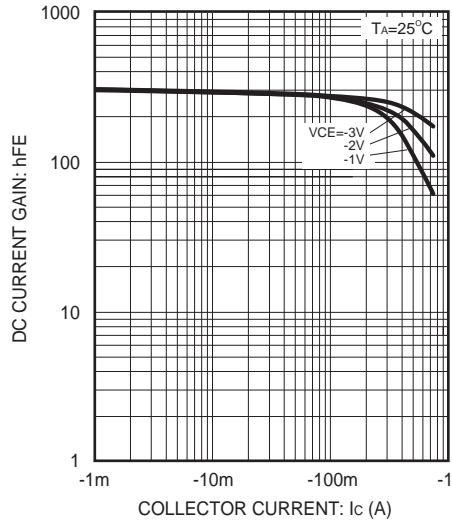
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$BV_{CBO}$	collector-base breakdown voltage	$I_E = 0; I_C = -50\text{ }\mu\text{A}$	-40	–	V
$BV_{CEO}$	collector-emitter breakdown voltage	$I_B = 0; I_C = -1\text{ mA}$	-32	–	V
$BV_{EBO}$	emitter-base breakdown voltage	$I_C = 0; I_E = -50\text{ }\mu\text{A}$	-5	–	V
$I_{CBO}$	collector cut-off current	$I_E = 0; V_{CB} = -20\text{ V}$	–	-500	nA
$I_{EBO}$	emitter cut-off current	$I_C = 0; V_{EB} = -4\text{ V}$	–	-500	nA
$h_{FE}$	DC current gain	$V_{CE} = -3\text{ V};$ note 1 $I_C = -100\text{ mA}$	120	390	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -500\text{ mA}, I_B = -50\text{ mA}$	–	-500	mV
$C_c$	collector capacitance	$I_E = I_B = 0; V_{CB} = -10\text{ V}; f = 1\text{ MHz}$	12 <sub>Typ.</sub>	30	pF
$f_T$	transition frequency	$I_C = 10\text{ mA}; V_{CE} = -20\text{ V};$ $f = 100\text{ MHz}$	50	200 <sub>Typ.</sub>	MHz

#### Note

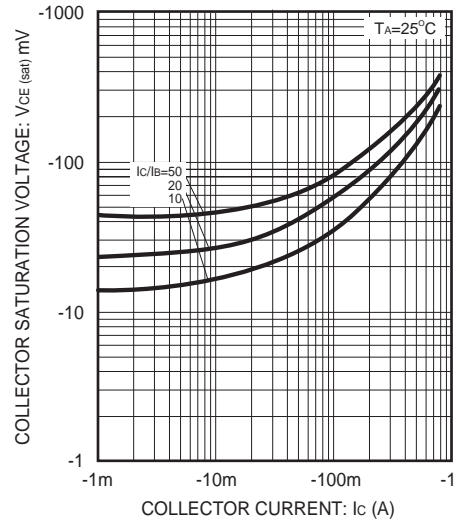
1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02.$
2.  $h_{FE}$ : Q Gade: 120~270  
R Gade: 180~390

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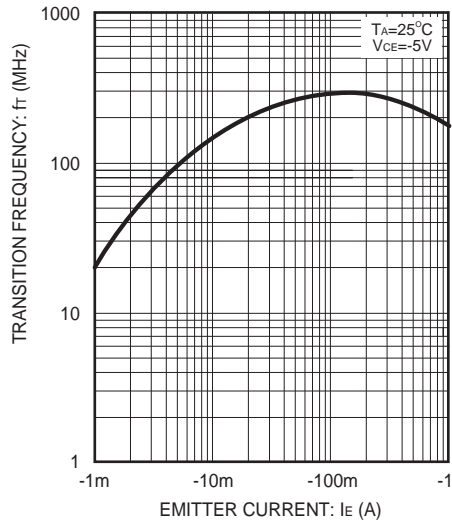
**Fig.1 DC Current gain vs. collector current**



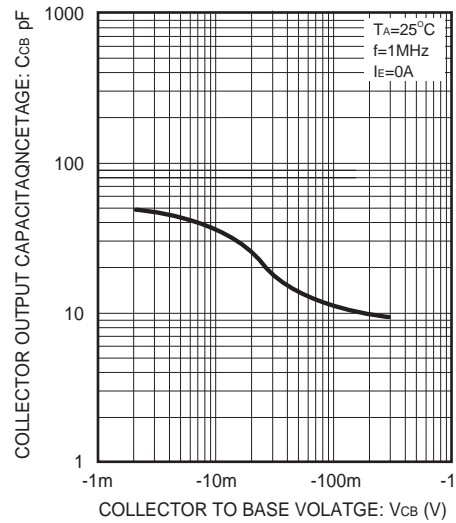
**Fig.2 Collector-emittersaturation voltage vs. collector current**



**Fig.3 Gain bandwidthproduct vs. emitter current**

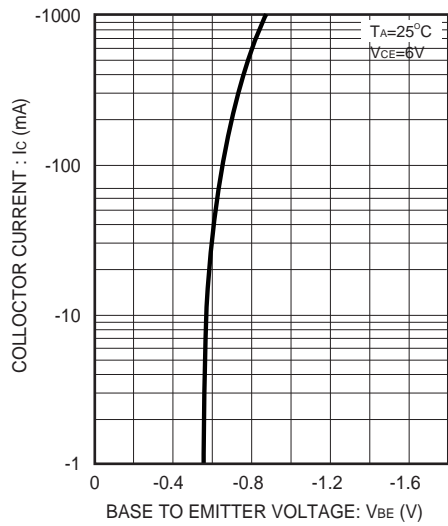


**Fig.4 Collector output capacitance**

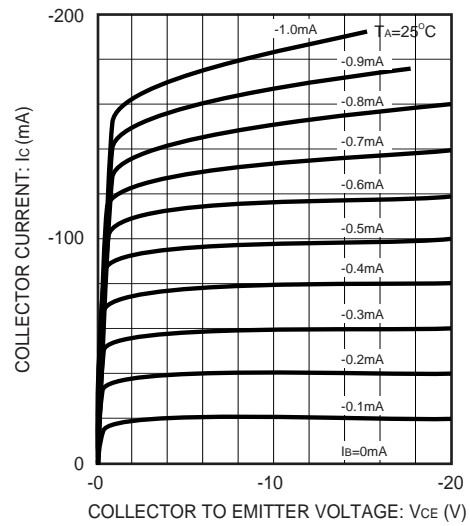


## RATING CHARACTERISTIC CURVES ( 2SB1197KPT )

**Fig.5 Grounded emitter propagation characteristics**



**Fig.6 Grounded emitter output characteristics**



**Fig.7 Grounded emitter output characteristics**

